# 1.1GHz Low Power Dual Modulus Prescaler
## With On-Chip Output Termination

**MC12022TSA**
**MC12022TSB**

**MECL PLL COMPONENTS**

**÷64/65, ÷128/129**
**DUAL MODULUS**
**PRESCALER**

The MC12022TSA can be used with CMOS synthesizers requiring positive edges to trigger internal counters such as Motorola's MC145XXX series in a PLL to provide tuning signals up to 1.1GHz in programmable frequency steps. This device is a reduced current drain version of the MC12022A/B with the addition of on–chip output termination.

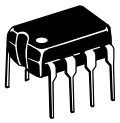
The MC12022TSB can be used with CMOS synthesizers requiring negative edges to trigger internal counters.

A Divide Ratio Control (SW) permits selection of a 64/65 or 128/129 divide ratio as desired.

The Modulus Control (MC) selects the proper divide number after SW has been biased to select the desired divide ratio.

***NOTE: The "B" Version Is Not Recommended for New Designs***

- 1.1 GHz Toggle Frequency
- Supply Voltage of 4.5 to 5.5V
- Low–Power 4.0mA Typical
- Operating Temperature Range of –40 to +85°C
- Short Setup Time ($t_{set}$) 16ns Maximum @ 1.1GHz
- Modulus Control Input Level Is Compatible With Standard CMOS and TTL
- Output Load Resistor on Die



**P SUFFIX**
8–LEAD PLASTIC PACKAGE
CASE 626–05

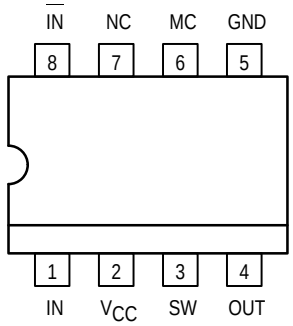
**D SUFFIX**
8–LEAD PLASTIC SOIC PACKAGE
CASE 751–05

**FUNCTIONAL TABLE**

| SW | MC | Divide Ratio |
|---|---|---|
| H | H | 64 |
| H | L | 65 |
| L | H | 128 |
| L | L | 129 |

Note: SW: H = $V_{CC}$, L = Open
MC: H = 2.0 V to $V_{CC}$, L = GND to 0.8 V

**Pinout: 8–Lead Plastic** (Top View)




**DESIGN GUIDE**

| Criteria | Value | Unit |
|---|---|---|
| Internal Gate Count* | 67 | ea |
| Internal Gate Propagation Delay | 200 | ps |
| Internal Gate Power Dissipation | 0.75 | mW |
| Speed Power Product | 0.15 | pJ |

* Equivalent to a two–input NAND gate

**MAXIMUM RATINGS**

| Symbol | Characteristic | Range | Unit |
|---|---|---|---|
| $V_{CC}$ | Power Supply Voltage, Pin 2 | –0.5 to + 7.0 | Vdc |
| $T_A$ | Operating Temperature Range | –40 to + 85 | °C |
| $T_{stg}$ | Storage Temperature Range | –65 to + 150 | °C |

**ELECTRICAL CHARACTERISTICS** ($V_{CC}$ = 4.5 to 5.5V; $T_A$ = –40°C to +85°C)

| Symbol | Characteristic | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| $f_t$ | Toggle Frequency (Sine Wave Input) | 0.1 | 1.4 | 1.1 | GHz |
| $I_{CC}$ | Supply Current (Pin 2) | | 4.6 | 6.5 | mA |
| $V_{IH1}$ | Modulus Control Input High (MC) | 2.0 | | $V_{CC}$ | V |
| $V_{IL1}$ | Modulus Control Input Low (MC) | | | 0.8 | V |
| $V_{IH2}$ | Divide Ratio Control Input High (SW) | $V_{CC}$ | $V_{CC}$ | $V_{CC}$ | Vdc |
| $V_{IL2}$ | Divide Ratio Control Input Low (SW) | Open | Open | Open | — |
| $V_{out}$ | Output Voltage Swing ($C_L$ = 8pF) | 1.0 | 1.4 | | $V_{p–p}$ |
| $t_{set}$ | Modulus Setup Time MC to Out | | 11 | 16 | ns |
| $V_{in}$ | Input Voltage Sensitivity 250–1100 MHz<br>100–250 MHz | 100<br>400 | | 1500<br>1500 | mVpp |

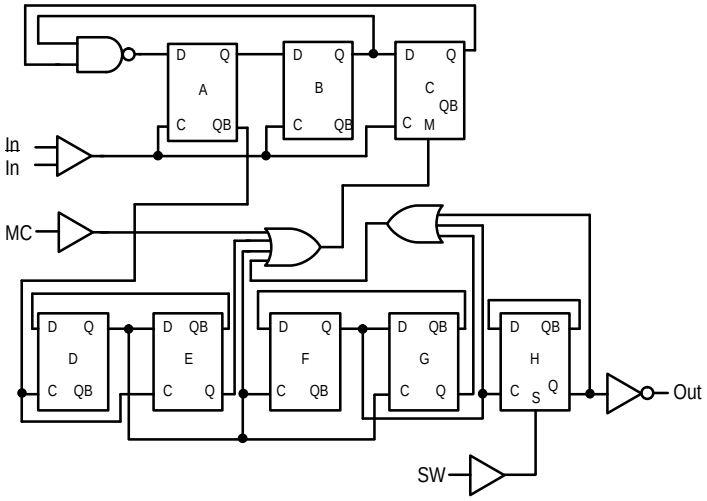
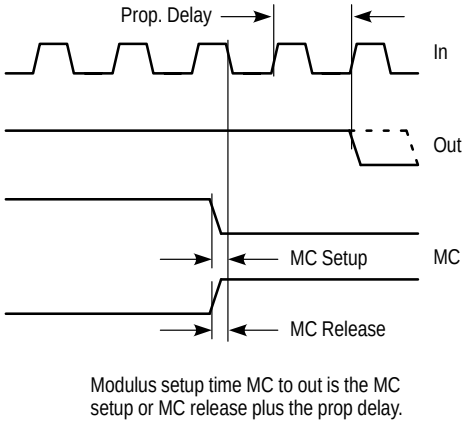
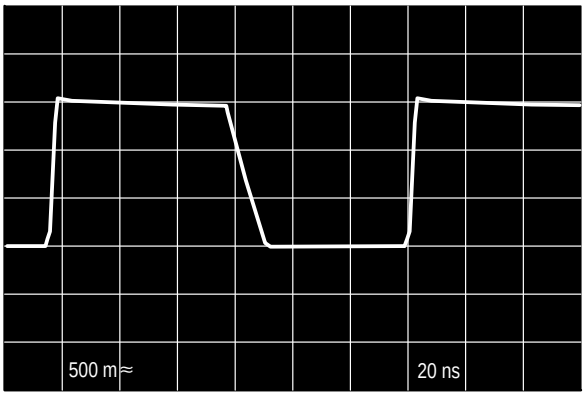



**Figure 1. Logic Diagram (MC12022TSA)**

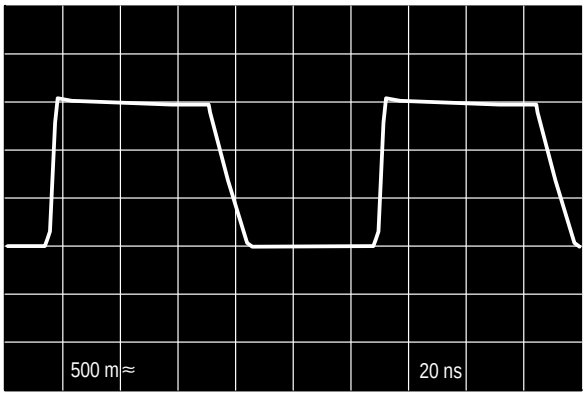



Modulus setup time MC to out is the MC setup or MC release plus the prop delay.

**Figure 2. Modulus Setup Time**




(÷64, 500MHz Input Frequency, $V_{CC}$ = 5.0V, $T_A$ = 25°C, Output Loaded)




(÷128, 1.1GHz Input Frequency, $V_{CC}$ = 5.0V, $T_A$ = 25°C, Output Loaded)

**Figure 3. Typical Output Waveforms**

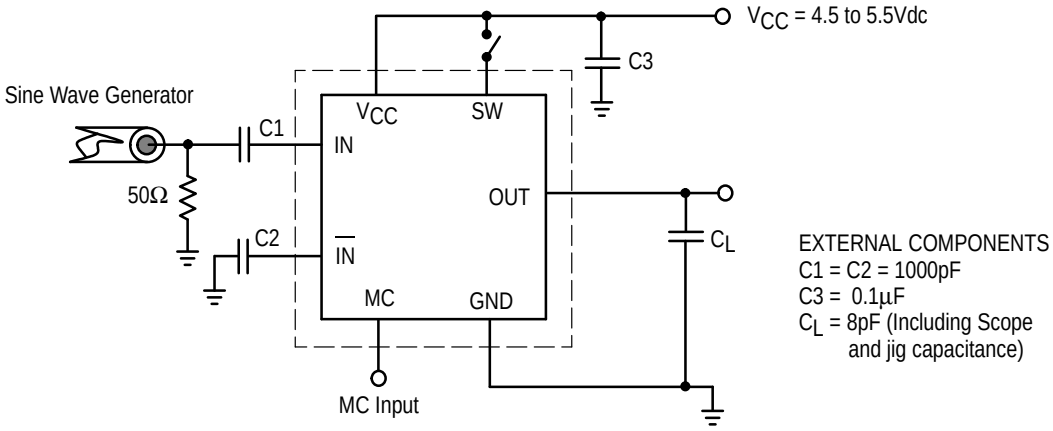



**Figure 4. AC Test Circuit**

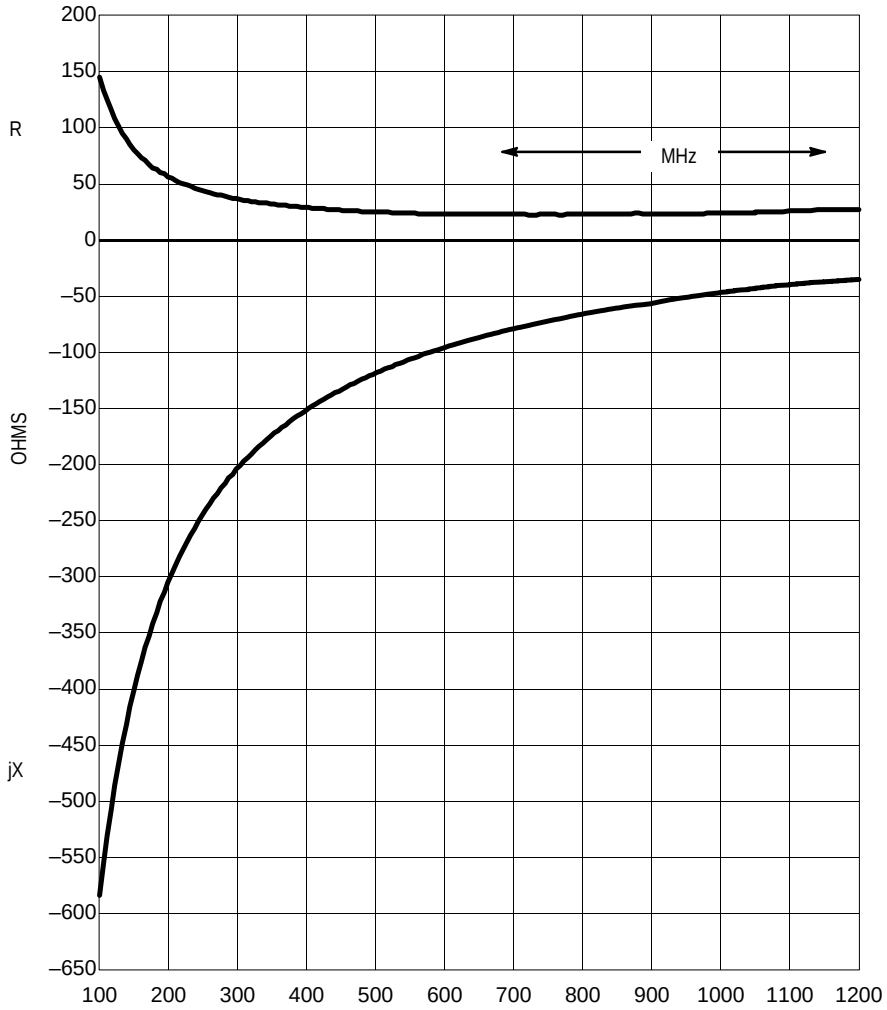
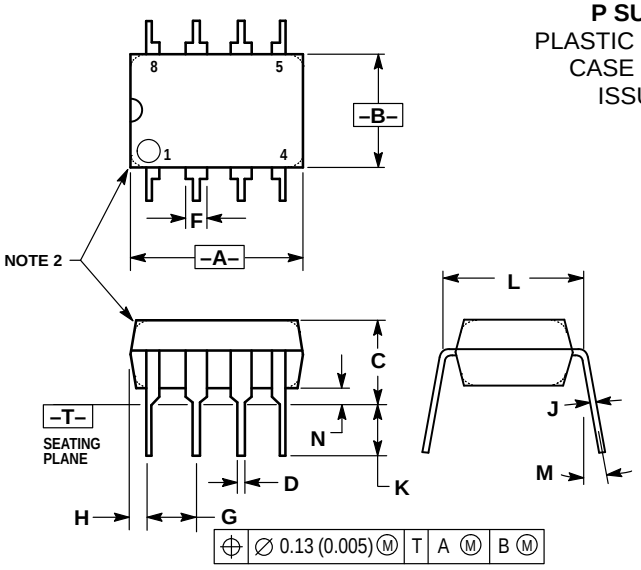



**Figure 5. Typical Input Impedance versus Input Frequency**

## OUTLINE DIMENSIONS

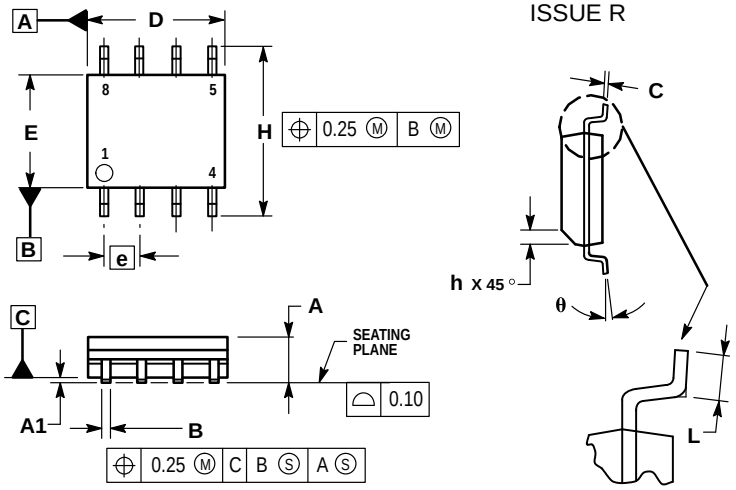
**P SUFFIX**
PLASTIC PACKAGE
CASE 626–05
ISSUE K




NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

| | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 9.40 | 10.16 | 0.370 | 0.400 |
| B | 6.10 | 6.60 | 0.240 | 0.260 |
| C | 3.94 | 4.45 | 0.155 | 0.175 |
| D | 0.38 | 0.51 | 0.015 | 0.020 |
| F | 1.02 | 1.78 | 0.040 | 0.070 |
| G | 2.54 BSC | | 0.100 BSC | |
| H | 0.76 | 1.27 | 0.030 | 0.050 |
| J | 0.20 | 0.30 | 0.008 | 0.012 |
| K | 2.92 | 3.43 | 0.115 | 0.135 |
| L | 7.62 BSC | | 0.300 BSC | |
| M | — | 10° | — | 10° |
| N | 0.76 | 1.01 | 0.030 | 0.040 |

**D SUFFIX**
PLASTIC SOIC PACKAGE
CASE 751–05
ISSUE R




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

| | MILLIMETERS | |
|---|---|---|
| DIM | MIN | MAX |
| A | 1.35 | 1.75 |
| A1 | 0.10 | 0.25 |
| B | 0.35 | 0.49 |
| C | 0.18 | 0.25 |
| D | 4.80 | 5.00 |
| E | 3.80 | 4.00 |
| e | 1.27 BSC | |
| H | 5.80 | 6.20 |
| h | 0.25 | 0.50 |
| L | 0.40 | 1.25 |
| θ | 0° | 7° |



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